

TRADEMARK ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Release of Security Interest in Intellectual Property Collateral

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
Bank of America, N.A., successor by merger to LaSalle Business Credit, Inc., as agent		12/22/2010	national banking association: UNITED STATES

RECEIVING PARTY DATA

Name:	Thermalloy, Inc.
Street Address:	70 Commercial Street
City:	Concord
State/Country:	NEW HAMPSHIRE
Postal Code:	03301
Entity Type:	CORPORATION: DELAWARE

Name:	Aavid Thermalloy, LLC
Street Address:	70 Commercial Street
City:	Concord
State/Country:	NEW HAMPSHIRE
Postal Code:	03301
Entity Type:	LIMITED LIABILITY COMPANY: DELAWARE

Name:	Aavid Laboratories, Inc.
Street Address:	70 Commercial Street
City:	Concord
State/Country:	NEW HAMPSHIRE
Postal Code:	03301
Entity Type:	CORPORATION: NEW HAMPSHIRE

Name:	Aavid Thermal Products, Inc.
Street Address:	70 Commercial Street
City:	Concord
State/Country:	NEW HAMPSHIRE

CH \$115.00 2101701

Postal Code:	03301
Entity Type:	CORPORATION: DELAWARE

PROPERTY NUMBERS Total: 4

Property Type	Number	Word Mark
Registration Number:	2101701	EASY-PLY
Registration Number:	1351654	INSUL-COTE
Registration Number:	2279929	OPTIPIN
Registration Number:	1028661	T

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	309642.0001
NAME OF SUBMITTER:	Jessica Davis
Signature:	/JDavis/
Date:	04/07/2011

Total Attachments: 11
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**RELEASE OF SECURITY INTEREST
IN INTELLECTUAL PROPERTY COLLATERAL**

This **RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY COLLATERAL** (this "Release"), dated as of December 22, 2010, is made by BANK OF AMERICA, N.A., as successor by merger to LaSalle Business Credit, Inc., as agent (the "Agent"), under the Loan and Security Agreement referred to below (terms used in this Release and not herein defined shall have the meanings set forth in the Loan Agreement).

WHEREAS, in connection with that certain Loan and Security Agreement, dated as of July 31st, 2002 (as amended, restated, supplemented or otherwise modified from time to time, and together with all general security agreements, trademark security agreements, patent security agreements and copyright security agreements entered into in connection therewith or in connection with prior versions thereof, the "Loan Agreement"), among THERMALLOY, INC., AAVID THERMALLOY, LLC, AAVID LABORATORIES, INC. and AAVID THERMAL PRODUCTS, INC. (collectively, the "Borrowers"), the other Credit Parties signatory thereto, the Agent, and the Lenders signatory thereto from time to time (each individually a "Lender," and collectively, the "Lenders"), the Lenders made credit extensions to the Borrowers;

WHEREAS, in connection with the Loan Agreement, and pursuant to those certain agreements described on Annex I attached hereto (collectively, the "Security Agreements"), the Borrowers and the Credit Parties granted security interests in certain intellectual property owned by the Borrowers and the Credit Parties including those listed on Annex I attached hereto (collectively, the "Intellectual Property Collateral"); and

WHEREAS, the Security Agreements were recorded in the U.S. Patent and Trademark Office or the Copyright Office on the dates and on the reels and frames set forth on Annex I hereto;

NOW THEREFORE, the Agent hereby **RELEASES**, without representation, recourse or warranty whatsoever, all of its security interest in the Intellectual Property Collateral, whether granted pursuant to the Security Agreements or any other agreement or document delivered in connection with the Loan Agreement, and the Agent hereby reassigns any and all such right, title and interest (if any) that the Agent may have in the Intellectual Property Collateral to the Borrowers and the Credit Parties, respectively.


The Agent agrees, at the Borrowers' and the Credit Parties' expense, to cooperate with the Borrowers and the Credit Parties and to provide the Borrowers and the Credit Parties with the information and additional authorization reasonably required or desirable to effect the release of the Agent's security interest in the released collateral described herein.

This Release and the rights and obligations of the parties hereto shall be governed by, and construed and interpreted in accordance with, the laws of the State of Illinois.

[Signature Page Follows]

IN WITNESS WHEREOF, the Agent has executed this Release as of the date first above written.

BANK OF AMERICA, N.A., as Agent, as successor
by merger to LaSalle Business Credit, Inc., as Agent

By: 
Name: Chris Greco
Title: Vice President

ANNEX I

The Trademark Security Agreement, dated as of July 31st, 2002, by Thermalloy, Inc. in favor of Bank of America, N.A., as Agent, as successor by merger to LaSalle Business Credit, inc., as Agent, which was recorded with the U.S. Patent and Trademark Office on August 26, 2002 at Reel/Frame No. 2568/0855.

U.S. Trademark Registrations/Applications	
Registration No.	Trademark
2,101,701	EASY-PLY
1,351,654	INSUL-COTE in Design
2,279,929	OPTIPIN
1,028,661	T (Design)

The Patent Security Agreement, dated as of July 31st, 2002, by Thermalloy, Inc. in favor of Bank of America, N.A., as Agent, as successor by merger to LaSalle Business Credit, Inc., as Agent, which was recorded with the U.S. Patent and Trademark Office on August 26, 2002 at Reel/Frame 013203/0862.

U.S. Patent Registrations/Applications	
Registration No.	Patent
6,082,440	HEAT DISSIPATION SYSTEM HAVING RELEASABLE ATTACHMENT ASSEMBLY
4,745,456	HEAT SINK CLIP ASSEMBLY
4,446,504	MOUNTING MEANS WITH SOLDERABLE STUDS
09/608,800	STRAP SPRING FOR ATTACHING HEAT SINKS TO CIRCUIT BOARDS TYPE DIV2

The Patent Security Agreement, dated as of July 31st, 2002, by Aavid Thermalloy, LLC in favor of Bank of America, NA., as Agent, as successor by merger to LaSalle Business Credit, Inc., as Agent, which was recorded with the U.S. Patent and Trademark Office on August 26, 2002 at Reel/Frame 013158/0901 and the Patent Security Agreement dated as of September 29, 2006 by Aavid Thermalloy, LLC in favor of Bank of America, N.A., as Agent, as successor by merger to LaSalle Business Credit, Inc., as Agent which was recorded with the U.S. Patent and Trademark Office on October 25, 2006 at Reel/Frame 018433/0104.

U.S. Patent Registrations/Applications	
Registration No.	Patent
6,286,586	TORSION BAR CLAMP APPARATUS AND METHOD FOR IMPROVING THERMAL AND MECHANICAL CONTACT BETWEEN STACKED ELECTRONIC COMPONENTS, Type DIV
6,178,628	HEAT SKINK FOR DIRECT ATTACHMENT TO SURFACE MOUNT ELECTRONIC DEVICE PACKAGES, Type CIP
4,884,331	METHOD OF MANUFACTURING HEAT SINK APPARATUS, Type CON
4,879,891	METHOD OF MANUFACTURING HEAT SINK APPARATUS, Type DIV
5,486,980	METHOD AND APPARATUS FOR DISSIPATING THERMAL ENERGY
5,386,338	HEAT SINK ATTACHMENT ASSEMBLY, Type NEW
5,428,897	HEAT SINK ATTACHMENT ASSEMBLY, Type DIV
5,566,749	STAMPED AND FORMED HEAT SINK
6,097,603	HEAT SINK FOR DIRECT ATTACHMENT TO SURFACE MOUNT ELECTRONIC DEVICE PACKAGES, Type NEW
4,602,315	COMPENSATING ROLL PIN FOR HEAT SINK MOUNTING, Type NEW
4,806,064	COMPENSATING ROLL PIN FOR HEAT SINK MOUNTING, Type CON
4,783,899	COMPENSATING ROLL PIN FOR HEAT SINK MOUNTING, Type DIV
5,371,652	SPRING CLAMP ASSEMBLY WITH ELECTRICALLY INSULATING SHOE, Type CIP
5,594,624	SPRING CLAMP ASSEMBLY WITH ELECTRICALLY INSULATING SHOE, Type R62
5,889,653	SPRING CLAMP ASSEMBLY WITH ELECTRICALLY INSULATING SHOE, Type DIV
6,115,253	STRAP SPRING FOR HEAT SINK CLIP ASSEMBLY
5,464,054	SPRING CLAMP AND HEAT SINK ASSEMBLY

5,276,585	HEAT SINK MOUNTING APPARATUS
5,068,764	ELECTRONIC DEVICE PACKAGE MOUNTING ASSEMBLY
5,019,940	MOUNTING APPARATUS FOR ELECTRONIC DEVICE PACKAGES
5,038,858	FINNED HEAT SINK AND METHOD OF MANUFACTURE
5,466,970	HOOKEED SPRING CLIP
5,130,888	SPRING CLIP FASTENER FOR SURFACE MOUNTING OF PRINTED CIRCUIT BOARD COMPONENTS
5,138,524	APPARATUS FOR SECURING ELECTRONIC DEVICE PACKAGES TO HEAT SINKS
5,019,942	INSULATING APPARATUS FOR ELECTRONIC DEVICE ASSEMBLIES
4,847,449	ALIGNMENT APPARATUS FOR USE IN MOUNTING ELECTRONIC COMPONENTS AND HEAT SINKS ON CIRCUIT BOARDS
D312,819	HEAT SINK OR SIMILAR ARTICLE, Type CON
D300,738	HEAT SINK OR SIMILAR ARTICLE, Type NEW
D357,227	SPRING CLIP FOR RETAINING THERMAL CONTACT BETWEEN AN ELECTRONIC DEVICE PACKAGE AND A HEAT SINK
4,609,040	SELF-SECURING HEAT SINK
4,625,260	FASTENERS FOR SURFACE MOUNTING OF PRINTED CIRCUIT BOARD COMPONENTS
5,930,114	HEAT SINK MOUNTING ASSEMBLY FOR SURFACE MOUNT ELECTRONIC DEVICE PACKAGES
5,847,928	STRAP SPRING FOR ATTACHING HEAT SINKS TO CIRCUIT BOARDS, Type NEW
6,313,993	STRAP SPRING FOR ATTACHING HEAT SINKS TO CIRCUIT BOARDS, Type CON
6,195,880	STRAP SPRING FOR ATTACHING HEAT SINKS TO CIRCUIT BOARDS, Type DIV
6,143,076	APPLICATOR HEAD
6,059,116	HEAT SINK PACKAGING DEVICE
5,897,917	PRE-APPLICATION OF GREASE TO HEAT SINKS WITH A PROTECTIVE COVERING, Type DIV
5,590,025	FAN ATTACHMENT CLIP FOR HEAT SINK, Type NEW
5,677,829	FAN ATTACHMENT CLIP FOR HEAT SINK, Type CIP
6,118,657	FAN ATTACHMENT CLIP FOR HEAT SINK, Type DIV
5,991,154	ATTACHMENT OF ELECTRONIC DEVICE PACKAGES TO HEAT

	SINKS
5,844,312	SOLDERABLE TRANSISTOR CLIP AND HEAT SINK
5,640,305	ANCHOR FOR SECURING A HEAT SINK TO A PRINTED CIRCUIT BOARD
5,572,789	PROCESS FOR FORMING A PROFILED ELEMENT, Type CEQ
5,590,712	HEAT SINK
5,774,964	PROCESS AND AN APPARATUS FOR FORMING A PROFILED ELEMENT, Type DIV2
5,903,977	METHOD AND AN APPARATUS FOR MANUFACTURING HEAT SINK DEVICES
5,422,789	PRINTED CIRCUIT BOARD COMPONENT MOUNTING DEVICE
5,650,662	DIRECT BONDED HEAT SPREADER
6,079,486	SPRING CLIP FOR ATTACHING AN ELECTRONIC COMPONENT TO A HEAT SINK AND AN ASSEMBLY UTILIZING THE SAME
6,435,266	HEAT-PIPE TYPE RADIATOR AND METHOD FOR PRODUCING THE SAME
7,306,027	FLUID-CONTAINING COOLING PLATE FOR AN ELECTRONIC COMPONENT
6,996,363	HEATING ROLLER OF A FIXING DEVICE WITH TWO INTERNAL HEATERS FOR AXIAL HEAT DISTRIBUTION
7,059,391	MULTIPLE EVAPORATOR HEAT PIPE ASSISTED HEAT SINK
5,466,970	HOOKEED SPRING CLIP
6,520,248	HEAT SINK HAVING BONDED COOLING FINS
6,747,865	HEAT SINK FOR ELECTRONIC COMPONENTS
6,661,658	FLUID-COOLED HEAT SINK FOR ELECTRONIC COMPONENTS
7,059,391	MULTIPLE EVAPORATOR HEAT PIPE ASSISTED HEAT SINK

Application No.	Patent
09/835,897	NOTCHED FINNED HEAT SINK STRUCTURE
09/859,715	HEAT SINK HAVING BONDED COOLING FINS
09/848,016	CHANNEL CONNECTION FOR PIPE TO BLOCK JOINTS
10/508,435	SUPPORT CLIP
11/053,098	LIQUID COLD PLATE HEAT EXCHANGER
08/669,875	COATING
09/939,356	HEAT SINK
60/328,330	HEAT COLLECTOR WITH MOUNTING PLATE
10/121,337	FLUID-COOLED HEAT SINK FOR ELECTRONIC COMPONENTS (BLISTER LIQUID COLD PLATE)
10/121,177	HEAT SINK FOR ELECTRONIC COMPONENTS (BRAIZED GAIN)

The Patent Security Agreement, dated as of July 31st, 2002, by Aavid Laboratories, Inc., in favor of Bank of America, N.A., as Agent, as successor by merger to LaSalle Business Credit, Inc., as Agent, which was recorded with the U.S. Patent and Trademark Office on August 26, 2002 at Reel/Frame 013203/0852.

U.S. Patent Registrations/Applications	
Registration No.	Patent
5,560,423	FLEXIBLE HEAT PIPE FOR INTEGRATED CIRCUIT APPARATUS
5,502,582	LIGHT SOURCE COOLER FOR LCD MONITOR
5,485,671	METHOD OF MAKING A TWO-PHASE THERMAL BAG COMPONENT COOLER, Type R62
5,720,338	TWO-PHASE THERMAL BAG COMPONENT COOLER, Type DIV
5,458,189	TWO-PHASE COMPONENT COOLER, Type NEW
5,704,416	TWO-PHASE COMPONENT COOLER, Type CIP
5,472,043	TWO-PHASE COMPONENT COOLER RADIOACTIVE INITIATOR
5,383,340	TWO-PHASE COOLING SYSTEM FOR LAPTOP COMPUTERS, Type NEW
5,634,351	TWO-PHASE COOLING SYSTEM FOR LAPTOP COMPUTERS, Type CIP
5,587,880	COMPUTER COOLING SYSTEM OPERABLE UNDER THE FORCE OF GRAVITY IN FIRST ORIENTATION AND AGAINST THE FORCE OF GRAVITY IN SECOND ORIENTATION

The Patent Security Agreement, dated as of July 31st, 2002, by Aavid Thermal Products, Inc., in favor of Bank of America, N.A., as Agent, as successor by merger to LaSalle Business Credit, Inc., as Agent, which was recorded with the U.S. Patent and Trademark Office on August 26, 2002 at Reel/Frame 013203/0933, the First Supplement to Patent Security Agreement, dated as of September 29, 2006, by Aavid Thermal Products, Inc., in favor of Bank of America, N.A., as Agent, as successor by merger to LaSalle Business Credit, Inc., as Agent, which was recorded with the U.S. Patent and Trademark Office on October 25, 2006 at Reel/Frame 018433/0990, the Patent Security Agreement by Aavid Thermal Products, Inc., as successor to Aavid Engineering, Inc., in favor of Bank of America, N.A., as Agent, as successor by merger to LaSalle Business Credit, Inc., as Agent, which was recorded with the U.S. Patent and Trademark office on October 7, 1996, at Reel/Frame 008059/0087, as amended.

U.S. Patent Registrations/Applications	
Registration No.	Patent
5,661,637	THERMAL MANAGEMENT SYSTEM HAVING A THERMALLY CONDUCTIVE SHEET AND A LIQUID TRANSPORTIVE MATERIAL
5,791,770	LIGHT SOURCE COOLER FOR LCD MONITOR
5,829,516	LIQUID COOLED HEAT SINK FOR COOLING ELECTRONIC COMPONENTS
6,229,706	REVERSE CANTILEVER SPRING CLIP
5,384,940	SELF-LOCKING HEAT SINKS FOR SURFACE MOUNT DEVICES
5,437,561	SELF-LOCKING TAB
D 307,540	CLIP FOR UNITING AN ELECTRONIC DEVICE WITH AN EXTRUDED HEAT SINK
5,285,350	HEAT SINK PLATE FOR MULTIPLE SEMI-CONDUCTORS
4,544,942	HEAT SINKS WITH STAKED SOLDERABLE STUDS
5,040,096	HIGH FORCE CLIP
4,933,746	THREE-LEGGED CLIP
5,570,271	HEAT SINK ASSEMBLIES
4,508,163	HEAT SINKS FOR INTEGRATED CIRCUIT MODULES
4,964,198	V-SHAPED CLIP FOR ATTACHING A SEMICONDUCTOR DEVICE TO A HEAT SINK
D 317,907	CLIP-ON HEAT SINK FOR AN ELECTRONIC DEVICE
D 303,951	HEAT SINK COVER FOR LEADLESS ELECTRONIC CHIP-CARRIER SOCKETS
D322,594	CLIP-ON WINGED HEAT SINK FOR AN ELECTRONIC DEVICE
D 303,786	SPRING-CLIP HEAT SINK FOR A PAIR OF ELECTRONIC DEVICES
D 314,945	HEAT SINK

D 304,293	SOLDERABLE MOUNT FOR AN ELECTRONIC DEVICE
D 313,399	HEAT SINK WITH SPRING CLIP
4,203,488	SELF-FASTENED HEAT SINKS
5,040,096	HIGH FORCE CLIP
5,297,005	APPARATUS AND METHOD FOR COOLING HEAT GENERATING ELECTRONIC COMPONENTS IN A CABINET
5,304,735	HEAT SINK FOR AN ELECTRONIC PIN GRIP ARRAY
5,570,271	HEAT SINK ASSEMBLIES
5,384,940	SELF-LOCKING HEAT SINKS FOR SURFACE MOUNT DEVICES
5,437,561	SELF-LOCKING TAB
5,285,350	HEAT SINK PLATE FOR MULTIPLE SEMI-CONDUCTORS